

Title (en)

Process for producing metal-bonded-ceramic materials or components.

Title (de)

Prozess zur Herstellung von metallbondierten Keramikmaterialien oder Komponenten.

Title (fr)

Procédé de fabrication de matériaux ou de composants avec une liaison directe métal-céramique.

Publication

**EP 0676800 A2 19951011 (EN)**

Application

**EP 95105372 A 19950410**

Priority

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Abstract (en)

Ceramic members 2 are fed successively into crucible 7 through guide 6A on the entrance side; after they are fully wetted by molten metal 1 in the crucible 7, the ceramic members 2 enter die 6B on the exit side, from which they are extruded successively with a metal part being joined to the surface of each ceramic member 2. This process assures that metal-bonded-ceramic (MBC) material or components 5 of many various shapes having satisfactory characteristics are manufactured at low cost; additionally, electronic circuit substrates can be fabricated from such MBC material 5. <IMAGE>

IPC 1-7

**H01L 21/48**; **H01L 23/373**

IPC 8 full level

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CPC (source: EP KR US)

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